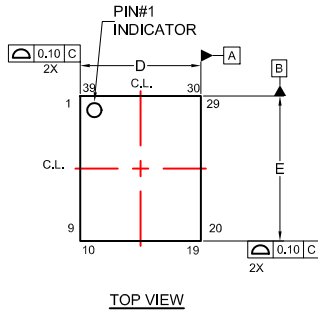
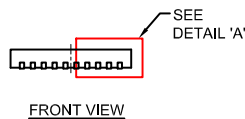


PQFN39 5X6, 0.45P
CASE 483BF
ISSUE B

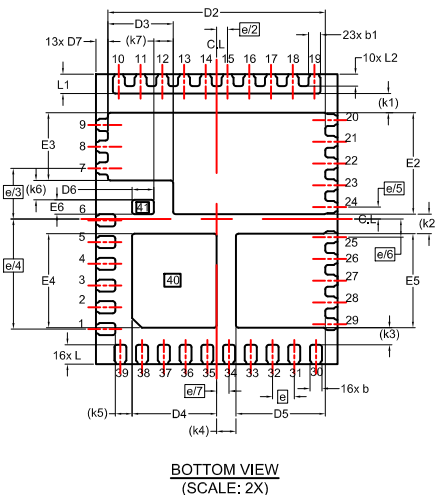
DATE 13 AUG 2019



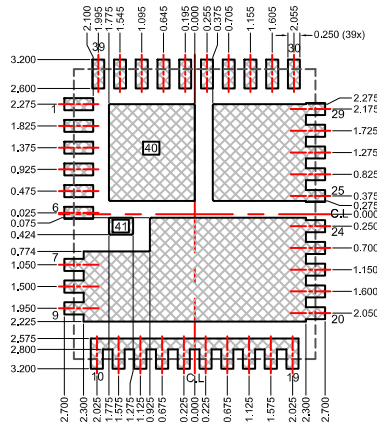
TOP VIEW



FRONT VIEW

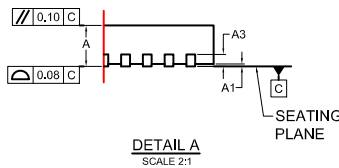


BOTTOM VIEW
(SCALE: 2X)



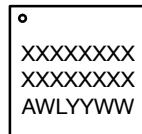
LAND PATTERN
RECOMMENDATION*

*FOR ADDITIONAL INFORMATION ON OUR
Pb-FREE STRATEGY AND SOLDERING DETAILS,
PLEASE DOWNLOAD THE ON SEMICONDUCTOR
SOLDERING AND MOUNTING TECHNIQUES
REFERENCE MANUAL, SOLDERRM/D.



DETAIL A
SCALE 2:1

GENERIC
MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

NOTES: UNLESS OTHERWISE SPECIFIED

- A) DOES NOT FULLY CONFORM TO JEDEC REGISTRATION MO-220, DATED MAY/2005.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	-	0.05
A3	0.15	0.20	0.25
b	0.20	0.25	0.30
b1	0.20	0.25	0.30
D	4.90	5.00	5.100
D2	4.40	4.50	4.60
D3	1.25	1.35	1.45
D4	1.65	1.75	1.85
D5	1.75	1.85	1.95
D6	0.35	0.45	0.55
D7	0.15	0.25	0.35
E	5.90	6.00	6.10
E2	2.00	2.10	2.20
E3	1.30	1.40	1.50
E4	1.85	1.95	2.05
E5	1.85	1.95	2.05
E6	0.20	0.30	0.40
e	0.450 BSC		
e/2	0.225 BSC		
e/3	1.050 BSC		
e/4	2.275 BSC		
e/5	0.250 BSC		
e/6	0.375 BSC		
e/7	0.255 BSC		
L	0.30	0.40	0.50
L1	0.30	0.40	0.50
L2	0.15	0.25	0.35
k1	0.40 REF		
k2	0.40 REF		
k3	0.35 REF		
k4	0.40 REF		
k5	0.35 REF		
k6	0.40 REF		
k7	0.40 REF		

DOCUMENT NUMBER:	98AON13685G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	PQFN39 5X6, 0.45P	PAGE 1 OF 1

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.